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SEMICONDUCTOR PACKAGE FOR ENHANCING HEAT DISSIPATION**ABSTRACT OF THE DISCLOSURE**

The present invention discloses a semiconductor package for enhancing heat dissipation. Only the structures of the semiconductor package that conventionally located in one of the two parts of the mold conventionally used to encapsulate a semiconductor package are encapsulated. A heat sink of the desired thickness is then attached to leads in the plurality of leads connected to the encapsulated die and possibly also to the die pad or leadframe with a thermally conductive and electrically insulating adhesive glue. As the thickness of the heat sink can be freely varied according to user's needs, the present invention is advantageous for manufacturing thin packages. Since the width of the heat sink covers the die pad and a part of the plurality of leads, the heat generated by the die is not only dissipated to the atmosphere from the heat sink connected to the leads of the leadframe to the air, but also dissipated through the printed circuit board connected to the leads of the leadframe to the air.